



CY7C1399

32K x 8 3.3V Static RAM

Features

- Single 3.3V power supply
- Ideal for low-voltage cache memory applications
- High speed
 - 12/15 ns
- Low active power
 - 255 mW (max.)
- Low CMOS standby power (L)
 - 180 μ W (max.), $f=f_{MAX}$
- 2.0V data retention (L)
 - 40 μ W
- Low-power alpha immune 6T cell
- Plastic SOJ and TSOP packaging

Functional Description

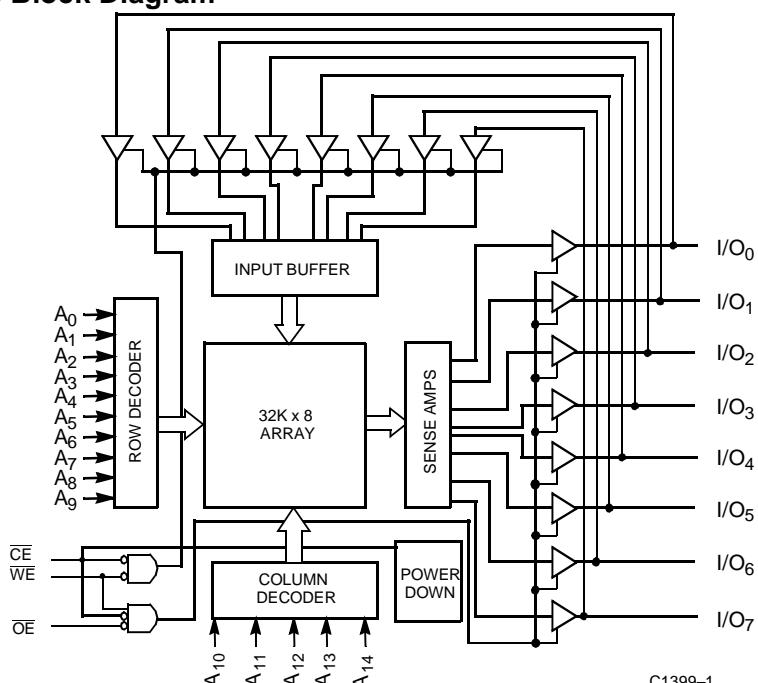
The CY7C1399 is a high-performance 3.3V CMOS Static RAM organized as 32,768 words by 8 bits. Easy memory expansion

is provided by an active LOW Chip Enable (\overline{CE}) and active LOW Output Enable (\overline{OE}) and three-state drivers. The device has an automatic power-down feature, reducing the power consumption by more than 95% when deselected.

An active LOW Write Enable signal (\overline{WE}) controls the writing/reading operation of the memory. When \overline{CE} and \overline{WE} inputs are both LOW, data on the eight data input/output pins (I/O₀ through I/O₇) is written into the memory location addressed by the address present on the address pins (A₀ through A₁₄). Reading the device is accomplished by selecting the device and enabling the outputs, \overline{CE} and \overline{OE} active LOW, while WE remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and Write Enable (WE) is HIGH. The CY7C1399 is available in 28-pin standard 300-mil-wide SOJ and TSOP Type I packages.

Logic Block Diagram



Pin Configurations

| SOJ Top View | |
|------------------|----|
| A ₆ | 1 |
| A ₆ | 2 |
| A ₇ | 3 |
| A ₈ | 4 |
| A ₉ | 5 |
| A ₁₀ | 6 |
| A ₁₁ | 7 |
| A ₁₂ | 8 |
| A ₁₃ | 9 |
| A ₁₄ | 10 |
| I/O ₀ | 11 |
| I/O ₁ | 12 |
| I/O ₂ | 13 |
| I/O ₃ | 14 |
| V _{CC} | 28 |
| WE | 27 |
| A ₄ | 26 |
| A ₃ | 25 |
| A ₂ | 24 |
| A ₁ | 23 |
| \overline{OE} | 22 |
| A ₀ | 21 |
| \overline{CE} | 20 |
| I/O ₇ | 19 |
| I/O ₆ | 18 |
| I/O ₅ | 17 |
| I/O ₄ | 16 |
| I/O ₃ | 15 |
| GND | |

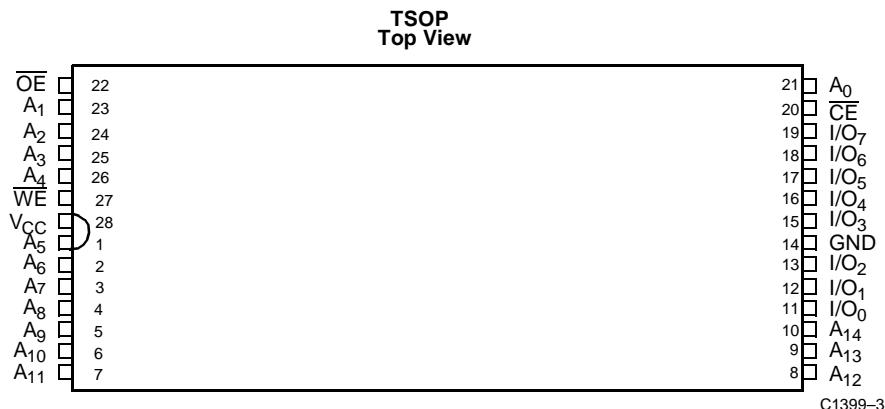
C1399-2

C1399-1

Selection Guide

| | 7C1399-12 | 7C1399-15 | 7C1399-20 | 7C1399-25 | 7C1399-35 |
|---|-----------|-----------|-----------|-----------|-----------|
| Maximum Access Time (ns) | 12 | 15 | 20 | 25 | 35 |
| Maximum Operating Current (mA) | 60 | 55 | 50 | 45 | 40 |
| Maximum CMOS Standby Current (μ A) | 500 | 500 | 500 | 500 | 500 |
| Maximum CMOS Standby Current (μ A) L | 50 | 50 | 50 | 50 | 50 |

Pin Configuration



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with

Power Applied -55°C to +125°C

Supply Voltage on V_{CC} to Relative GND^[1] -0.5V to +4.6V

DC Voltage Applied to Outputs
in High Z State^[1] -0.5V to V_{CC} + 0.5V

DC Input Voltage^[1] -0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW) 20 mA

Static Discharge Voltage >2001V
(per MIL-STD-883, Method 3015)

Latch-Up Current >200 mA

Operating Range

| Range | Ambient Temperature | V _{CC} |
|------------|---------------------|-----------------|
| Commercial | 0°C to +70°C | 3.3V ±300 mV |
| Industrial | -40°C to +85°C | 3.3V ±300 mV |

Electrical Characteristics Over the Operating Range^[1]

| Parameter | Description | Test Conditions | 7C1399-12 | | 7C1399-15 | | 7C1399-20 | | Unit |
|------------------|--|--|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|------|
| | | | Min. | Max. | Min. | Max. | Min. | Max. | |
| V _{OH} | Output HIGH Voltage | V _{CC} = Min., I _{OH} = -2.0 mA | 2.4 | | 2.4 | | 2.4 | | V |
| V _{OL} | Output LOW Voltage | V _{CC} = Min., I _{OL} = 4.0 mA | | 0.4 | | 0.4 | | 0.4 | V |
| V _{IH} | Input HIGH Voltage | | 2.2 | V _{CC} +0.3V | 2.2 | V _{CC} +0.3V | 2.2 | V _{CC} +0.3V | V |
| V _{IL} | Input LOW Voltage | | -0.3 | 0.8 | -0.3 | 0.8 | -0.3 | 0.8 | V |
| I _{IX} | Input Load Current | | -1 | +1 | -1 | +1 | -1 | +1 | µA |
| I _{OZ} | Output Leakage Current | GND ≤ V _I ≤ V _{CC} , Output Disabled | -5 | +5 | -5 | +5 | -5 | +5 | µA |
| I _{OS} | Output Short Circuit Current ^[2] | V _{CC} = Max., V _{OUT} = GND | | -300 | | -300 | | -300 | mA |
| I _{CC} | V _{CC} Operating Supply Current | V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC} | | 60 | | 55 | | 50 | mA |
| I _{SB1} | Automatic CE Power-Down Current — TTL Inputs | Max. V _{CC} , $\overline{CE} \geq V_{IH}$, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = f _{MAX} | | 5 | | 5 | | 5 | mA |
| | | | L | 3 | | 3 | | 3 | |
| I _{SB2} | Automatic CE Power-Down Current — CMOS Inputs ^[3] | Max. V _{CC} , $\overline{CE} \geq V_{CC} - 0.3V$, V _{IN} ≥ V _{CC} - 0.3V, or V _{IN} ≤ 0.3V, WE ≥ V _{CC} - 0.3V or WE ≤ 0.3V, f = f _{MAX} | | 500 | | 500 | | 500 | µA |
| | | | L | 50 | | 50 | | 50 | |

Notes:

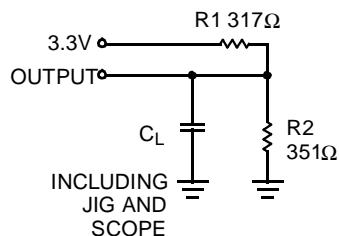
- Minimum voltage is equal to -2.0V for pulse durations of less than 20 ns.
- Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
- Device draws low standby current regardless of switching on the addresses.

Electrical Characteristics Over the Operating Range(continued)

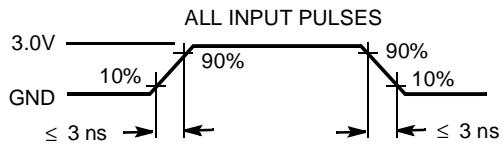
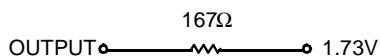
| Parameter | Description | Test Conditions | 7C1399-25 | | 7C1399-35 | | Unit |
|-----------|--|--|-----------|-----------------|-----------|-----------------|---------------|
| | | | Min. | Max. | Min. | Max. | |
| V_{OH} | Output HIGH Voltage | $V_{CC} = \text{Min.}$, $I_{OH} = -2.0 \text{ mA}$ | 2.4 | | 2.4 | | V |
| V_{OL} | Output LOW Voltage | $V_{CC} = \text{Min.}$, $I_{OL} = 4.0 \text{ mA}$ | | 0.4 | | 0.4 | V |
| V_{IH} | Input HIGH Voltage | | 2.2 | $V_{CC} + 0.3V$ | 2.2 | $V_{CC} + 0.3V$ | V |
| V_{IL} | Input LOW Voltage | | -0.3 | 0.8 | -0.3 | 0.8 | V |
| I_{IX} | Input Load Current | | -1 | +1 | -1 | +1 | μA |
| I_{OZ} | Output Leakage Current | $GND \leq V_I \leq V_{CC}$, Output Disabled | -5 | +5 | -5 | +5 | μA |
| I_{OS} | Output Short Circuit Current ^[2] | $V_{CC} = \text{Max.}$, $V_{OUT} = GND$ | | -300 | | -300 | mA |
| I_{CC} | V_{CC} Operating Supply Current | $V_{CC} = \text{Max.}$, $I_{OUT} = 0 \text{ mA}$, $f = f_{MAX} = 1/t_{RC}$ | | 45 | | 40 | mA |
| I_{SB1} | Automatic CE Power-Down Current — TTL Inputs | $\text{Max. } V_{CC}, \overline{CE} \geq V_{IH}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, $f = f_{MAX}$ | | 5 | | 5 | mA |
| | | | L | 3 | | 3 | mA |
| I_{SB2} | Automatic CE Power-Down Current — CMOS Inputs ^[3] | $\text{Max. } V_{CC}, \overline{CE} \geq V_{CC} - 0.3V, V_{IN} \geq V_{CC} - 0.3V$, or $V_{IN} \leq 0.3V$, $WE \geq V_{CC} - 0.3V$ or $WE \leq 0.3V$, $f = f_{MAX}$ | | 500 | | 500 | μA |
| | | | L | 50 | | 50 | μA |

Capacitance^[4]

| Parameter | Description | Test Conditions | Max. | Unit |
|----------------------|--------------------|---|------|------|
| C_{IN} : Addresses | Input Capacitance | $T_A = 25^\circ\text{C}$, $f = 1 \text{ MHz}$, $V_{CC} = 3.3\text{V}$ | 5 | pF |
| C_{IN} : Controls | | | 6 | pF |
| C_{OUT} | Output Capacitance | | 6 | pF |

AC Test Loads and Waveforms


Equivalent to: THÉVENIN EQUIVALENT



C1399-4

Note:

4. Tested initially and after any design or process changes that may affect these parameters.



CY7C1399

Switching Characteristics Over the Operating Range^[5]

| Parameter | Description | 7C1399-12 | | 7C1399-15 | | 7C1399-20 | | 7C1399-25 | | 7C1399-35 | | Unit |
|--------------------------------------|-------------------------------------|-----------|------|-----------|------|-----------|------|-----------|------|-----------|------|------|
| | | Min. | Max. | |
| READ CYCLE | | | | | | | | | | | | |
| t _{RC} | Read Cycle Time | 12 | | 15 | | 20 | | 25 | | 35 | | ns |
| t _{AA} | Address to Data Valid | | 12 | | 15 | | 20 | | 25 | | 35 | ns |
| t _{OHA} | Data Hold from Address Change | 3 | | 3 | | 3 | | 3 | | 3 | | ns |
| t _{ACE} | CE LOW to Data Valid | | 12 | | 15 | | 20 | | 25 | | 35 | ns |
| t _{DOE} | OE LOW to Data Valid | | 5 | | 6 | | 7 | | 8 | | 10 | ns |
| t _{LZOE} | OE LOW to Low Z ^[6] | 0 | | 0 | | 0 | | 0 | | 0 | | ns |
| t _{HZOE} | OE HIGH to High Z ^[6, 7] | | 5 | | 6 | | 6 | | 7 | | 7 | ns |
| t _{LZCE} | CE LOW to Low Z ^[6] | 3 | | 3 | | 3 | | 3 | | 3 | | ns |
| t _{HZCE} | CE HIGH to High Z ^[6, 7] | | 6 | | 7 | | 7 | | 8 | | 8 | ns |
| t _{PU} | CE LOW to Power-Up | 0 | | 0 | | 0 | | 0 | | 0 | | ns |
| t _{PD} | CE HIGH to Power-Down | | 12 | | 15 | | 20 | | 25 | | 35 | ns |
| WRITE CYCLE ^[8, 9] | | | | | | | | | | | | |
| t _{WC} | Write Cycle Time | 12 | | 15 | | 20 | | 25 | | 35 | | ns |
| t _{SCE} | CE LOW to Write End | 8 | | 10 | | 12 | | 15 | | 20 | | ns |
| t _{AW} | Address Set-Up to Write End | 8 | | 10 | | 12 | | 15 | | 20 | | ns |
| t _{HA} | Address Hold from Write End | 0 | | 0 | | 0 | | 0 | | 0 | | ns |
| t _{SA} | Address Set-Up to Write Start | 0 | | 0 | | 0 | | 0 | | 0 | | ns |
| t _{PWE} | WE Pulse Width | 8 | | 10 | | 12 | | 15 | | 20 | | ns |
| t _{SD} | Data Set-Up to Write End | 7 | | 8 | | 10 | | 11 | | 12 | | ns |
| t _{HD} | Data Hold from Write End | 0 | | 0 | | 0 | | 0 | | 0 | | ns |
| t _{HZWE} | WE LOW to High Z ^[8] | | 7 | | 7 | | 7 | | 7 | | 7 | ns |
| t _{LZWE} | WE HIGH to Low Z ^[6] | 3 | | 3 | | 3 | | 3 | | 3 | | ns |

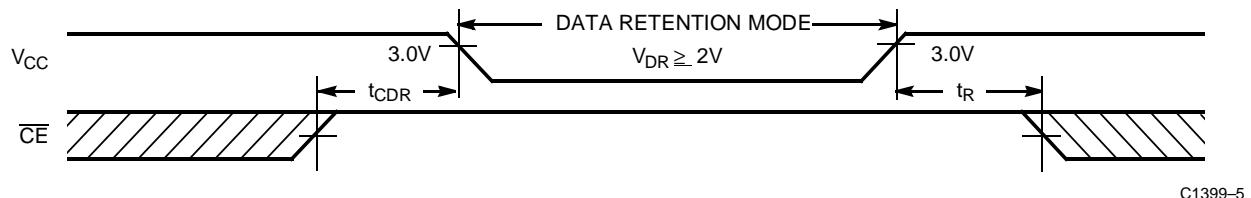
Data Retention Characteristics (Over the Operating Range)

| Parameter | Description | Conditions | Min. | Max. | Unit |
|---------------------------------|--------------------------------------|---|-----------------|------|------|
| V _{DR} | V _{CC} for Data Retention | | 2.0 | | V |
| I _{CCDR} | Data Retention Current | L $\frac{V_{CC} = V_{DR} = 2.0\text{V},}{CE \geq V_{CC} - 0.3\text{V},} \frac{V_{IN} \geq V_{CC} - 0.3\text{V or}}{V_{IN} \leq 0.3\text{V}}$ | | 200 | µA |
| | | | | 20 | µA |
| t _{CDR} ^[4] | Chip Deselect to Data Retention Time | | 0 | | ns |
| t _R ^[4] | Operation Recovery Time | | t _{RC} | | ns |

Notes:

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and capacitance $C_L = 30\text{ pF}$.
- At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
- t_{HZOE}, t_{HZCE}, t_{HZWE} are specified with C_L = 5 pF as in AC Test Loads. Transition is measured $\pm 500\text{ mV}$ from steady state voltage.
- The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
- The minimum write cycle time for write cycle #3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}.

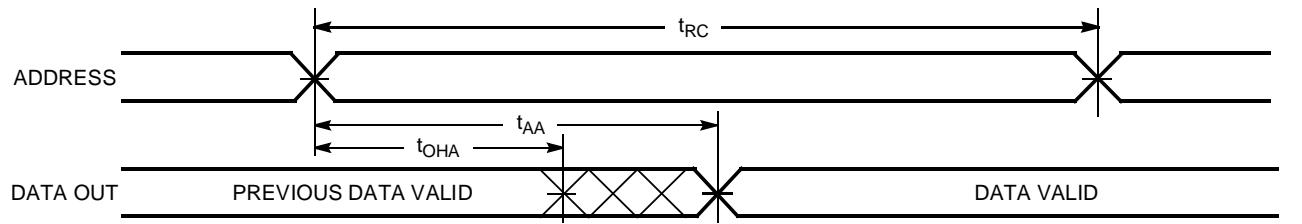
Data Retention Waveform



C1399-5

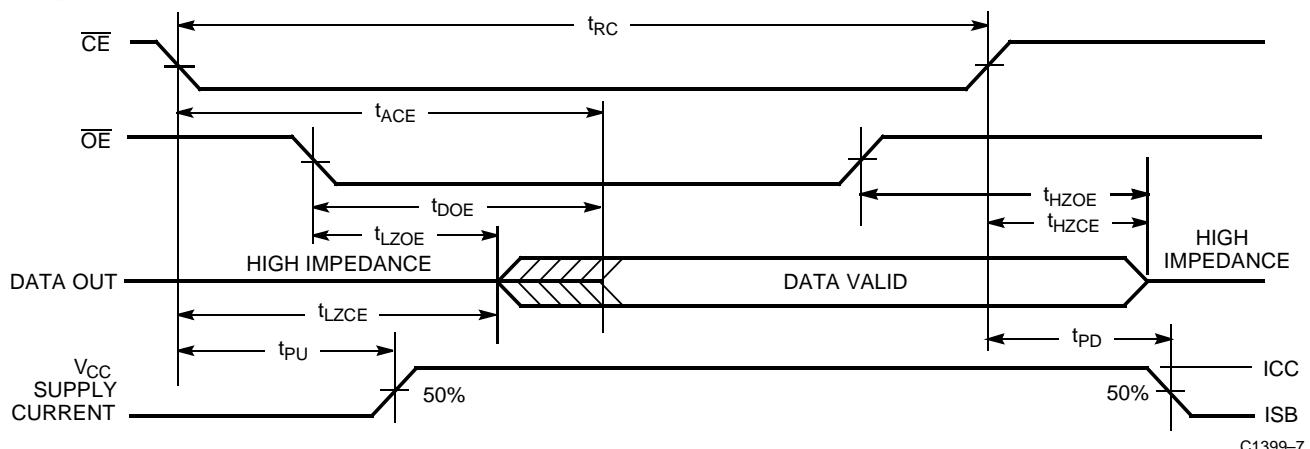
Switching Waveforms

Read Cycle No. 1^[10, 11]



C1399-6

Read Cycle No. 2^[11, 12]



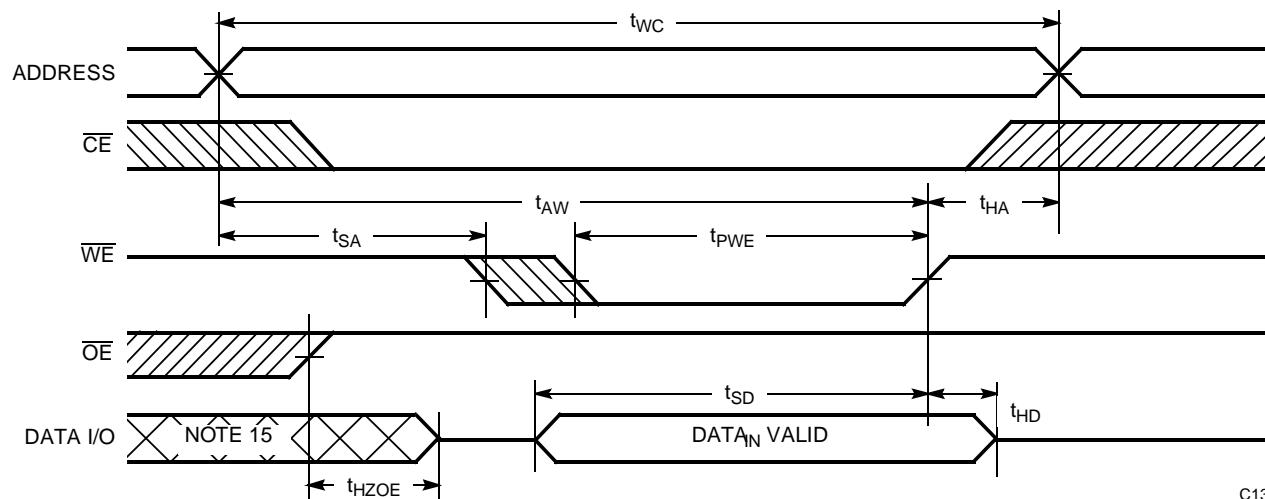
C1399-7

Notes:

10. Device is continuously selected. $\overline{OE}, \overline{CE} = V_{IL}$.
11. WE is HIGH for read cycle.
12. Address valid prior to or coincident with \overline{CE} transition LOW.

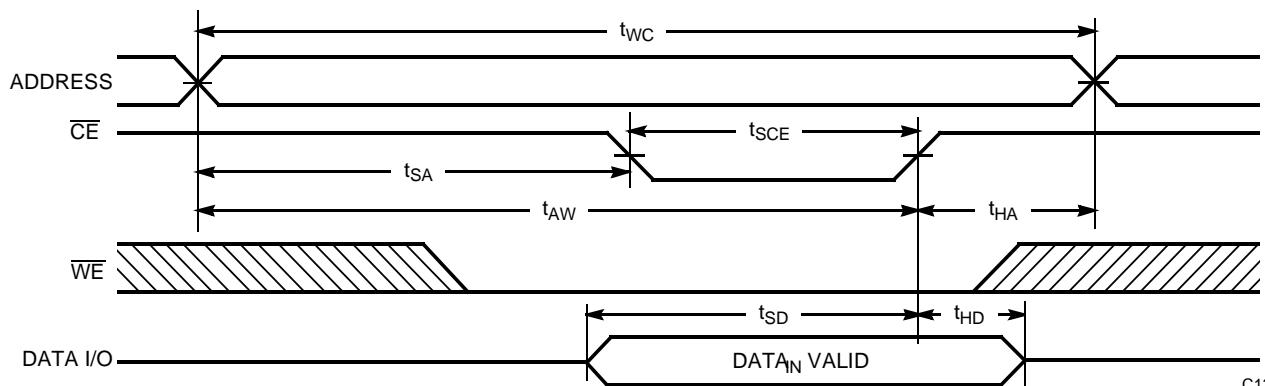
Switching Waveforms (continued)

Write Cycle No. 1 (\overline{WE} Controlled)^[8, 13, 14]



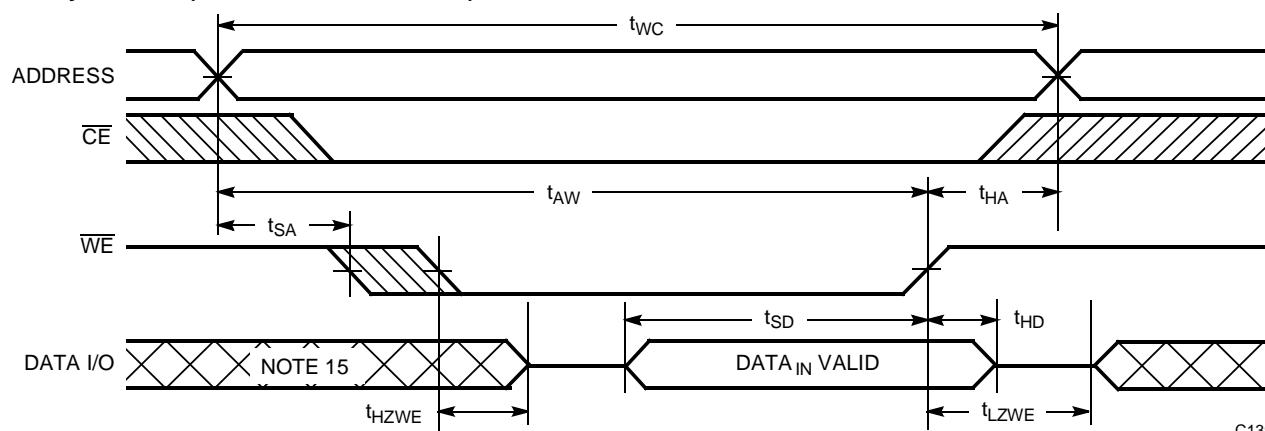
C1399-8

Write Cycle No. 2 (\overline{CE} Controlled)^[8, 13, 14]



C1399-9

Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW)^[9, 14]



C1399-10

Notes:

13. Data I/O is high impedance if $\overline{OE} = V_{IH}$.
14. If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.
15. During this period, the I/Os are in the output state and input signals should not be applied.

**CY7C1399****Truth Table**

| CE | WE | OE | Input/Output | Mode | Power |
|-----------|-----------|-----------|---------------------|---------------------------|----------------------|
| H | X | X | High Z | Deselect/Power-Down | Standby (I_{SB}) |
| L | H | L | Data Out | Read | Active (I_{CC}) |
| L | L | X | Data In | Write | Active (I_{CC}) |
| L | H | H | High Z | Deselect, Output Disabled | Active (I_{CC}) |

Ordering Information

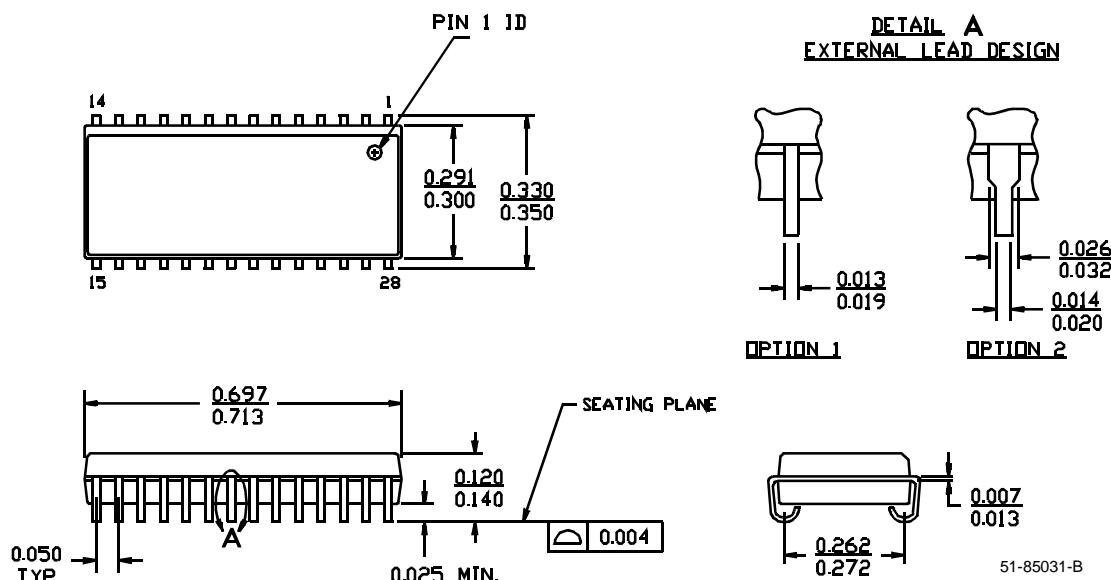
| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|-----------------------|----------------------|---------------------|------------------------------------|------------------------|
| 12 | CY7C1399-12VC | V21 | 28-Lead Molded SOJ | Commercial |
| | CY7C1399L-12VC | V21 | 28-Lead Molded SOJ | |
| | CY7C1399-12ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-12ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399-12VI | V21 | 28-Lead Molded SOJ | Industrial |
| | CY7C1399-12ZI | Z28 | 28-Lead Thin Small Outline Package | |
| 15 | CY7C1399-15VC | V21 | 28-Lead Molded SOJ | Commercial |
| | CY7C1399L-15VC | V21 | 28-Lead Molded SOJ | |
| | CY7C1399-15ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-15ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399-15VI | V21 | 28-Lead Molded SOJ | Industrial |
| | CY7C1399-15ZI | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-15ZI | Z28 | 28-Lead Thin Small Outline Package | |
| 20 | CY7C1399-20VC | V21 | 28-Lead Molded SOJ | Commercial |
| | CY7C1399L-20VC | V21 | 28-Lead Molded SOJ | |
| | CY7C1399-20ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-20ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399-20VI | V21 | 28-Lead Molded SOJ | Industrial |
| 25 | CY7C1399-25VC | V21 | 28-Lead Molded SOJ | Commercial |
| | CY7C1399L-25VC | V21 | 28-Lead Molded SOJ | |
| | CY7C1399-25ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-25ZC | Z28 | 28-Lead Thin Small Outline Package | |
| 35 | CY7C1399-35VC | V21 | 28-Lead Molded SOJ | Commercial |
| | CY7C1399L-35VC | V21 | 28-Lead Molded SOJ | |
| | CY7C1399-35ZC | Z28 | 28-Lead Thin Small Outline Package | |
| | CY7C1399L-35ZC | Z28 | 28-Lead Thin Small Outline Package | |

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Package Diagrams

28-Lead (300-Mil) Molded SOJ V21

DIMENSIONS IN INCHES MIN. MAX.



28-Lead Thin Small Outline Package Z28

NOTE: ORIENTATION I.D. MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2

